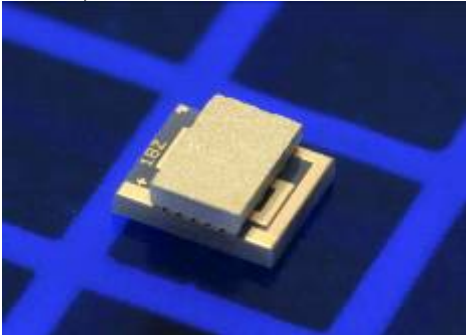


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Nextreme OptoCooler HV14 Module

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Microscale heat pump enables pinpoint thermal management at the heat source...

NEXTREME BREAKS TEMPERATURE BARRIER WITH THE OPTOCOOLER HV14

DURHAM, N.C. (March 24, 2009) — Nextreme Thermal Solutions, the leader in microscale thermal and power management products for the electronics industry, today announced that the OptoCooler HV14 is the industry's first high voltage, low current thin-film thermoelectric cooler (TEC) targeted at laser diode cooling for the telecommunications market to achieve a 60°C temperature difference between its cold and hot sides. This temperature difference, known as the ΔT , reflects the ability of the device to pump heat efficiently. For customers in the optoelectronics and telecommunications industries, this translates to improved cooling performance, lower input power requirements and greater efficiencies for solving thermal management issues in electronic packages.

The OptoCooler HV14 thermoelectric cooler is the first module in a new class of high voltage and high heat pumping thermoelectric coolers that operate at low currents and are optimized for standard circuitry and power requirements. The device can pump up to 1.5W of heat at 85°C and operates at a maximum voltage of 2.7 with a maximum current of around 1A; with a footprint of only 2.8mm². The module is ideally suited for the cooling and temperature control of optoelectronic devices such as laser diodes for transmission modules and photodiodes for sensing.

The improved performance is the result of recent advances in thin-film technology at Nextreme and reflects Nextreme's response to the market demand for thermoelectrics with higher ΔT s at ambient temperatures.

Bulk TEC devices have been used to provide temperature control of laser diodes and other optoelectronic devices. However, a major trend in photonics today has been the move to smaller form factor, higher power, and more integrated, cost-effective packaging in order to enable a lower cost structure while concurrently opening the door for higher volume manufacturing. In the course of this transition, conventional thermoelectric solutions have not kept pace with these needs due to their size and power density limitations.

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Nextreme Breaks Temperature Barrier with OptoCooler HV14, Page 2

Due to the micro-size and power-pumping capabilities of the HV14 module, manufacturers of LEDs and other semiconductor chips can now integrate cooling and temperature control functionality directly into the package during assembly, resulting in a high-volume, lower cost thermal management solution.

"The most efficient thermal management system involves embedding thermal management functionality at the source of the heat," said Dave Koester, vice president of engineering at Nextreme. "Introducing localized cooling in the package translates to a greater cost savings at the device and system levels."

"Breaking the 60°C ΔT barrier raises the bar in terms of improved efficiencies and lower operating costs," said Koester. "Devices with higher ΔT s require less operating power to achieve the desired cooling effect, which is significant for achieving a greener world."

Nextreme will be demonstrating its cooling and thermal management product family, including the HV14 module, at the Optical Fiber Communication Conference and Exposition and The National Fiber Optic Engineers Conference (OFC/NFOEC), March 24-26, 2009 in booth #3315 at the San Diego Convention Center.

The OptoCooler HV14 is RoHS compliant and is available for order now. Pricing is available upon request. More information on the OptoCooler HV14 can be found at www.nextreme.com/optocooler. Contact Nextreme at 3908 Patriot Dr., Suite 140, Durham, NC 27703-8031; call (919)-597-7300; e-mail info@nextreme.com; or go to www.nextreme.com.

About Nextreme Thermal Solutions™, Inc.

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products for the electronics, telecommunications, semiconductor, consumer, and defense/aerospace industries. The company uses breakthrough thin-film thermoelectric material to embed cooling, temperature control and power generation capabilities into the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's headquarters and manufacturing facility are based near Research Triangle Park, North Carolina.

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For additional information or to request the electronic image, please email beth.gaddy@btbmarketing.com or call 919-872-8172.